

### L-BAND PA DRIVER AMPLIFIER

#### DESCRIPTION

The  $\mu$ PG2130TB is GaAs MMIC for PA driver amplifier which were developed for mobile phone and another L-band application. The device can operate with 3.0 V TYP., having the high gain and low distortion.

#### FEATURES

- Operation frequency :  $f_{opt} = 1\ 429$  to  $1\ 453$  MHz (1 441 MHz TYP.)
- Supply voltage :  $V_{DD1} = 2.7$  to  $3.3$  V (3.0 V TYP.)  
:  $V_{DD2} = 3.0$  to  $4.2$  V (3.5 V TYP.)
- Circuit current :  $I_{DD} = 25$  mA TYP. @  $V_{DD1} = 3.0$  V,  $V_{DD2} = 3.2$  V,  $V_{AGC} = 2.5$  V,  $P_{out} = +10$  dBm
- High power gain :  $G_P = 30$  dB TYP. @  $V_{DD1} = 3.0$  V,  $V_{DD2} = 3.2$  V,  $V_{AGC} = 2.5$  V,  $P_{in} = -20$  dBm
- Gain control range :  $GCR = 42$  dB TYP. @  $V_{DD1} = 3.0$  V,  $V_{DD2} = 3.2$  V,  $V_{AGC} = 0.5$  to  $2.5$  V,  
 $P_{in} = -20$  dBm
- Low distortion :  $P_{adj1} = -60$  dBc TYP. @  $V_{DD1} = 3.0$  V,  $V_{DD2} = 3.2$  V,  $V_{AGC} = 2.5$  V,  $P_{out} = +10$  dBm,  
 $\Delta f = \pm 50$  kHz, 21 kHz Bandwidth.
- High-density surface mounting : 6-pin super minimold package ( $2.0 \times 1.25 \times 0.9$  mm)

#### APPLICATION

- Digital Cellular: PDC 1.5 GHz etc.

#### ORDERING INFORMATION

Part Number	Package	Marking	Supplying Form
$\mu$ PG2130TB-E3	6-pin super minimold	G2P	<ul style="list-style-type: none"> <li>• Embossed tape 8 mm wide</li> <li>• Pin 1, 2, 3 face the perforation side of the tape</li> <li>• Qty 3 kpcs/reel</li> </ul>

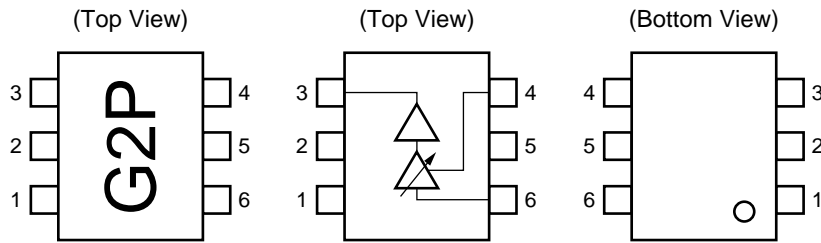
**Remark** To order evaluation samples, contact your nearby sales office.

Part number for sample order:  $\mu$ PG2130TB

#### Caution Electro-static sensitive devices

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.  
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

**PIN CONNECTIONS, MARKING AND INTERNAL BLOCK DIAGRAM**



Pin No.	Pin Name
1	V <sub>DD1</sub>
2	GND
3	OUTPUT/V <sub>DD2</sub>
4	V <sub>AGC</sub>
5	GND
6	INPUT

**ABSOLUTE MAXIMUM RATINGS (Unless otherwise specified, T<sub>A</sub> = +25°C)**

Parameter	Symbol	Ratings	Unit
Supply Voltage1, 2	V <sub>DD1, 2</sub>	6.0	V
AGC Control Voltage	V <sub>AGC</sub>	6.0	V
Input Power	P <sub>in</sub>	-8	dBm
Power Dissipation	P <sub>D</sub>	140 <sup>Note</sup>	mW
Operating Ambient Temperature	T <sub>A</sub>	-30 to +90	°C
Storage Temperature	T <sub>stg</sub>	-35 to +150	°C

**Note** Mounted on double copper-clad 50 × 50 × 1.6 mm epoxy glass PWB, T<sub>A</sub> = +85°C

**RECOMMENDED OPERATING RANGE (T<sub>A</sub> = +25°C)**

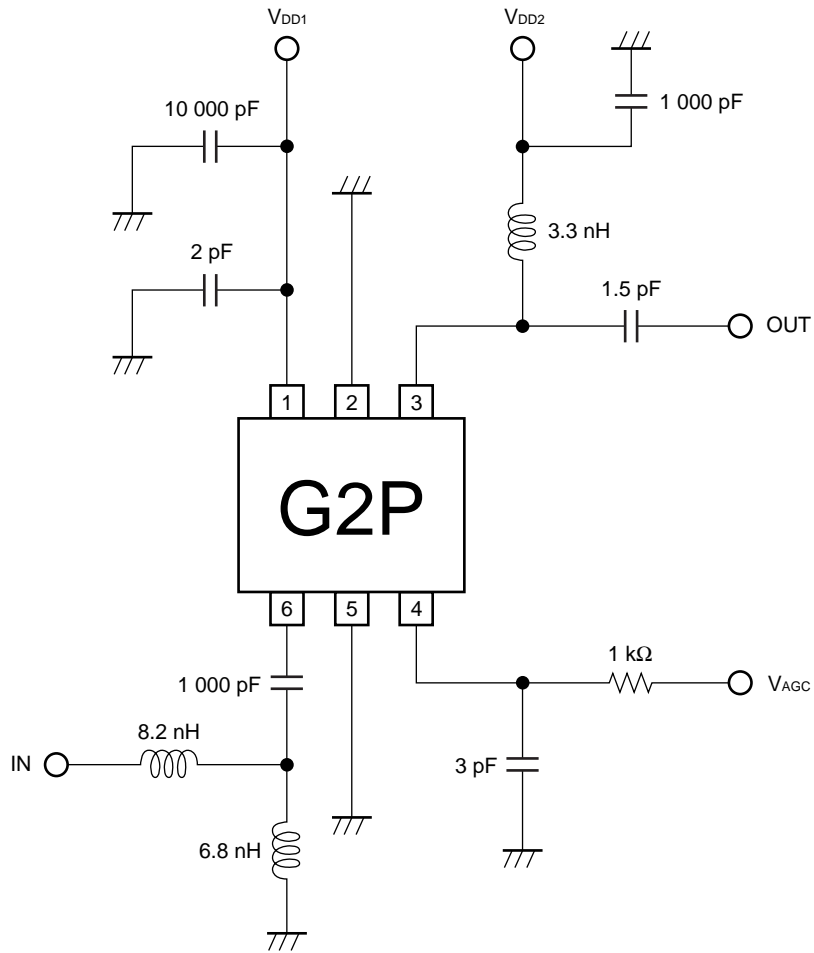
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage1	V <sub>DD1</sub>	2.7	3.0	3.3	V
Supply Voltage2	V <sub>DD2</sub>	3.0	3.5	4.2	V
AGC Control Voltage	V <sub>AGC</sub>	0	-	2.5	V
Input Power	P <sub>in</sub>	-	-18	-10	dBm

**ELECTRICAL CHARACTERISTICS**

(Unless otherwise specified, T<sub>A</sub> = +25°C, V<sub>DD1</sub> = 3.0 V, V<sub>DD2</sub> = 3.2 V, π/4DQPSK modulated signal input, External input and output matching)

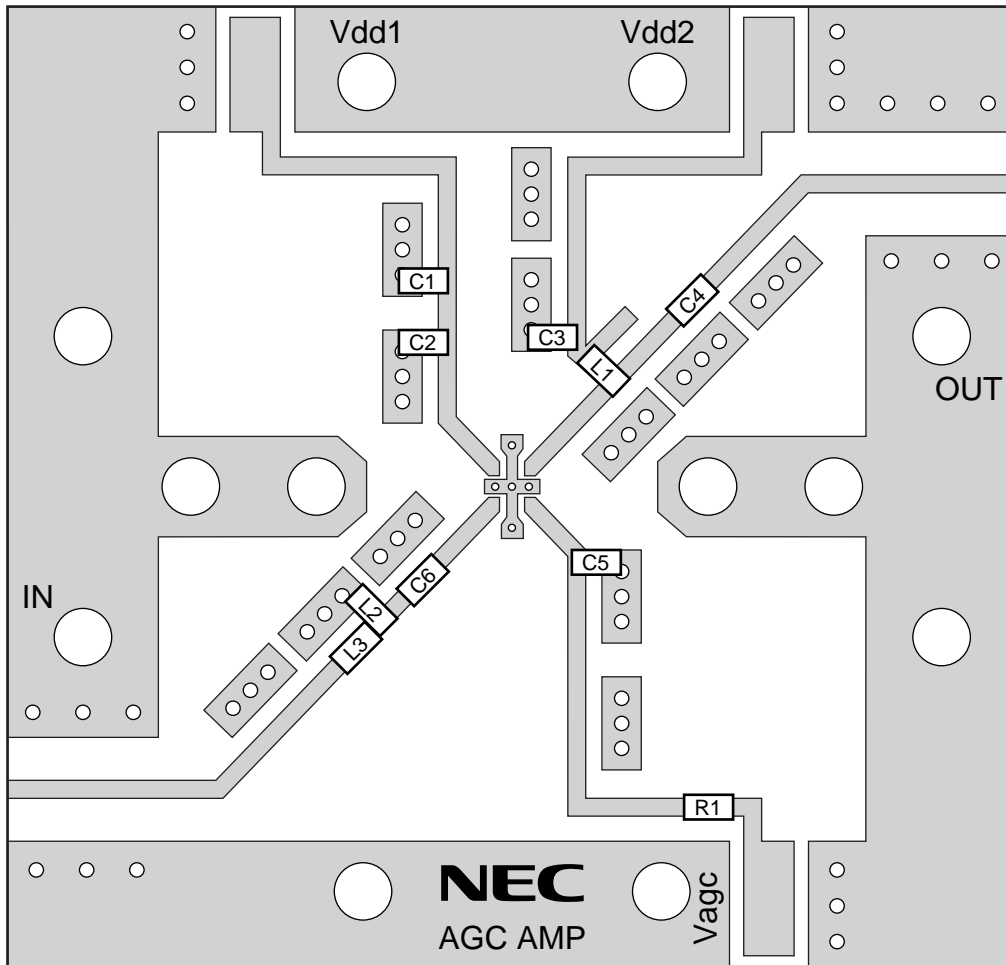
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Operating Frequency	f <sub>opt</sub>		1 429	–	1 453	MHz
Circuit Current	I <sub>DD</sub>	P <sub>out</sub> = +10 dBm, V <sub>AGC</sub> = 2.5 V	–	25	35	mA
Power Gain	G <sub>P</sub>	P <sub>in</sub> = -20 dBm, V <sub>AGC</sub> = 2.5 V	28	30	–	dB
Adjacent Channel Power Leakage 1	P <sub>adj1</sub>	P <sub>out</sub> = +10 dBm, V <sub>AGC</sub> = 2.5 V Δf = ±50 kHz, 21 kHz Bandwidth	–	-60	-55	dBc
Adjacent Channel Power Leakage 2	P <sub>adj2</sub>	P <sub>out</sub> = +10 dBm, V <sub>AGC</sub> = 2.5 V Δf = ±100 kHz, 21 kHz Bandwidth	–	-70	-65	dBc
Gain Control Range	GCR	P <sub>in</sub> = -20 dBm, V <sub>AGC</sub> = 0.5 to 2.5 V	37	42	–	dB
Gain Control Current	I <sub>AGC</sub>	V <sub>AGC</sub> = 0.5 to 2.5 V	–	200	500	μA

EVALUATION CIRCUIT ( $V_{DD1} = 3.0\text{ V}$ ,  $V_{DD2} = 3.2\text{ V}$ ,  $f = 1\,441\text{ MHz}$ )



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

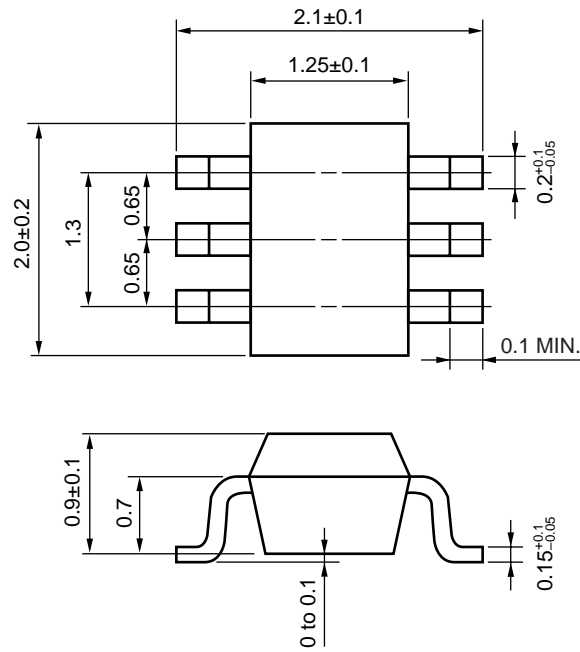


USING THE NEC EVALUATION BOARD

Symbol	Values	Part Number	Maker
L1	3.3 nH	TFL0816-3N3	Susumu
L2	6.8 nH	TFL0816-6N8	Susumu
L3	8.2 nH	TFL0816-8N2	Susumu
C1	10 000 pF	GRM39CH103J50	muRata
C3, C6	1 000 pF	GRM39CH102J50	muRata
C2	2 pF	GRM39CK020C50	muRata
C4	1.5 pF	GRM39CJ015C50	muRata
C5	3 pF	GRM39CJ030C50	muRata
R1	1 kΩ	RR0816	Susumu

PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



**RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

**Caution Do not use different soldering methods together (except for partial heating).**

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M8E 00.4-0110

**SAFETY INFORMATION ON THIS PRODUCT**

<p><b>Caution</b></p>	<p>GaAs Products</p>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> <li>• Do not destroy or burn the product.</li> <li>• Do not cut or cleave off any part of the product.</li> <li>• Do not crush or chemically dissolve the product.</li> <li>• Do not put the product in the mouth.</li> </ul> <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► **Business issue**

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► **Technical issue**

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